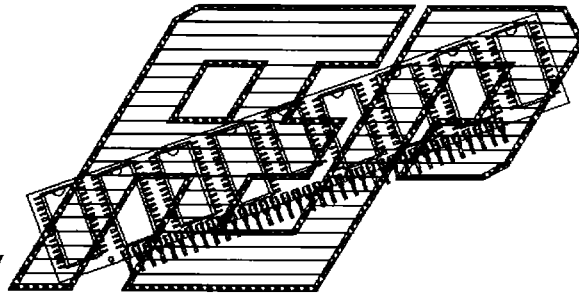


- >> 524,288 x 8 Organization
- >> Double sided to maximize bit density
- >> On board 1-of-16 Decoder
- >> Completely Static operation
- >> TTL compatible
- >> Low power, battery back-up operation capability
- >> Uses single +5V power supply
- >> Super Low Power version available



**512 KILOBYTES STATIC RAM MODULE**

**DESCRIPTION:**

The AEPSX512K8 is a high density 512 Kilo-word by 8 bit static random access memory module in a 36 pin single-inline-package format. Physically it consists of an FR4 PC material substrate mounted with sixteen 32K x 8 SOP (small outline package) ICs, the 1-of-16 decoder, four 0.1 microfarad decoupling capacitors, and 36 edge-clip I/O pins.

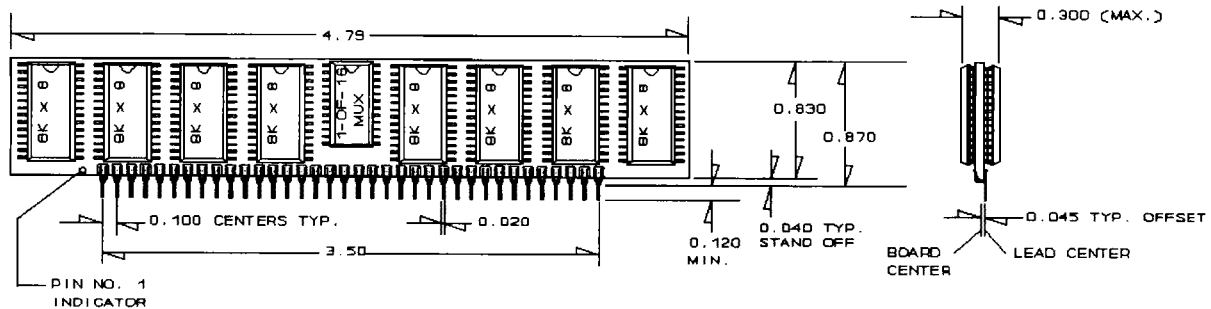
The module can use any of the 32K x 8 SRAMs made by any of a large number of manufacturers in both Mix-MOS and CMOS technologies. A wide range of access speeds are available. The decoder normally used is the 74HCT154. Other decoder choices available are the 74F154, the 74LS154, and the fully CMOS version 74HC154.

Performance specifications and electrical characteristics are determined by the IC devices used. A typical memory component on the module will draw 100uA (max.) in standby and 70mA (max.) during access (for standard low power devices, super low power use 2uA and 8mA typically).

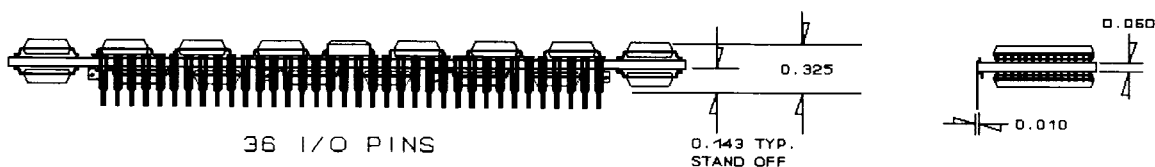
Mechanical dimensions are 0.88 in. high by 4.79 in. long by 0.30 in. wide. The module is available with either vertical or 90 degree (horizontal) lead pins. The latter allows the module to be mounted on its side which gives a low 0.325 stand-off height. This module is also available in 128K x 8 SRAM organization.

**SPECIFICATION DRAWING**

512K x 8 SRAM MODULE  
 DIMENSIONS IN INCHES, TOLERANCE: +/- 0.010 UNLESS SPECIFIED.



FRONT AND SIDE VIEWS  
 (SHOWING VERTICAL MOUNTING LEADS OPTION)



36 I/O PINS  
 (SHOWING HORIZONTAL MOUNTING LEADS OPTION)



512K x 8 STATIC RAM MODULE

SIP PIN-OUT CONFIGURATION

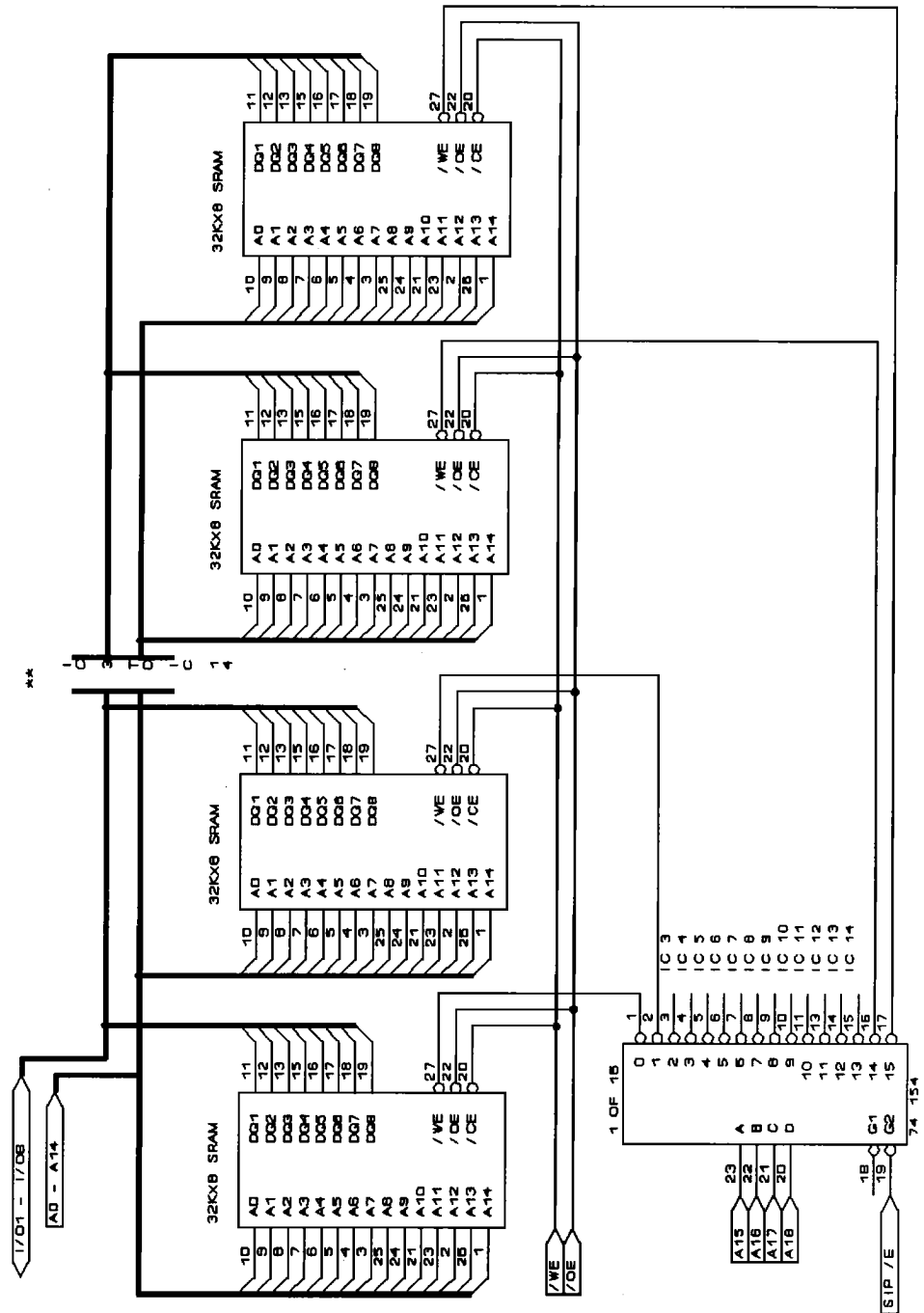
FUNCTIONAL DIAGRAM

- 1 — NC
- 2 — VCC
- 3 — WE\*
- 4 — I/O<sub>3</sub>
- 5 — I/O<sub>4</sub>
- 6 — I/O<sub>1</sub>
- 7 — A<sub>1</sub>
- 8 — A<sub>2</sub>
- 9 — A<sub>3</sub>
- 10 — A<sub>4</sub>
- 11 — GND
- 12 — I/O<sub>6</sub>
- 13 — A<sub>10</sub>
- 14 — A<sub>11</sub>
- 15 — A<sub>5</sub>
- 16 — A<sub>13</sub>
- 17 — A<sub>14</sub>
- 18 — NC
- 19 — SIPE\*
- 20 — A<sub>15</sub>
- 21 — A<sub>16</sub>
- 22 — A<sub>12</sub>
- 23 — A<sub>18</sub>
- 24 — A<sub>6</sub>
- 25 — I/O<sub>2</sub>
- 26 — GND
- 27 — A<sub>0</sub>
- 28 — A<sub>7</sub>
- 29 — A<sub>8</sub>
- 30 — A<sub>9</sub>
- 31 — I/O<sub>8</sub>
- 32 — I/O<sub>5</sub>
- 33 — I/O<sub>7</sub>
- 34 — A<sub>17</sub>
- 35 — VCC
- 36 — OE\*

\* ACTIVE WHEN LOW

128K x 8 version notes:  
pin 23 is a NO CONNECT.  
pin 34 is a CHIP SELECT (active low).

High address notes:  
address inputs A13 to A16 are connected to the decoder on both the 128K and the 512K versions. If compatibility between the two versions is not a concern, then it is recommended making these the highest order address lines when using the 512K module exclusively.



02 \*K010 Z0 10Z 14 CRI - 0 - \*\*

